ADOPTION NOTICE

IPC–2226, "Sectional Design Standard for High Density Interconnect (HDI) Printed Boards", was adopted on 13 March 2009 for use by the Department of Defense (DoD). Proposed changes by DoD activities must be submitted to the DoD Adopting Activity: Defense Logistics Agency, Defense Supply Center Columbus, P.O. Box 3990, ATTN: DSCC–VAC, Columbus, OH 43218–3990 or by electronic mail to: 5998.Documents@dla.mil. Copies of this standard may be purchased from the IPC – Association Connecting Electronics Industry (IPC), 3000 Lakeside Drive, Suite 309 S, Bannockburn, IL 60015–1249 or http://www.ipc.org.

Custodians:
Army – CR
Navy – EC
Air Force – 85
DLA – CC

Review activities:
Air Force – 99

Adopting activity:
DLA – CC

Project: 5998–2009–025

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at http://assist.daps.dla.mil/.